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SERIAL NUMBER 10/765,931	FILING or 371(c) DATE 01/29/2004 RULE	CLASS 228 438	GROUP ART UNIT 2823	ATTORNEY DOCKET NO. Q79041
APPLICANTS Youichi Kukimoto, Kakogawa-shi, JAPAN; Hitoshi Sakurai, Kakogawa-shi, JAPAN; Seishi Kumamoto, Kakogawa-shi, JAPAN; Kenshu Oyama, Kakogawa-shi, JAPAN; None /KN/				
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** FOREIGN APPLICATIONS ***** Yes /KN/ JAPAN 2003-110125 04/15/2003				
** IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 06/12/2004				
Foreign Priority claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No 35 USC 119(a-d) conditions met <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Verified and /KHIEM D NGUYEN/ Acknowledged Examiner's Signature	<input type="checkbox"/> Met after Allowance /KN/ Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWINGS 2	TOTAL CLAIMS 15 7
INDEPENDENT CLAIMS 3 2				
ADDRESS SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, DC 20037 UNITED STATES				
TITLE Solder deposition method and solder bump forming method				
FILING FEE RECEIVED 1640	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	